

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

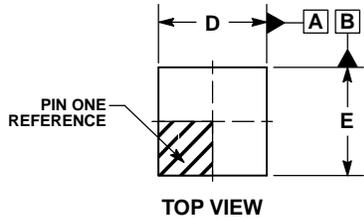
ON Semiconductor®



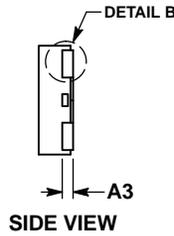
SCALE 4:1

XDFN4 1.2x1.2, 0.8P
CASE 711BC
ISSUE O

DATE 15 SEP 2015



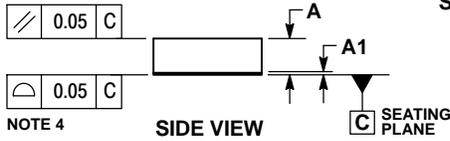
TOP VIEW



SIDE VIEW

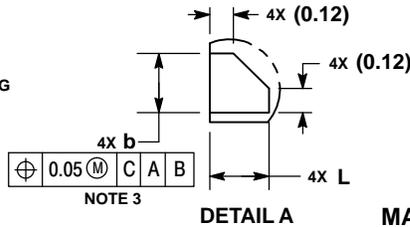


DETAIL B
ALTERNATE
CONSTRUCTION



SIDE VIEW

NOTE 4



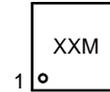
DETAIL A

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 mm FROM THE TERMINAL TIPS.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

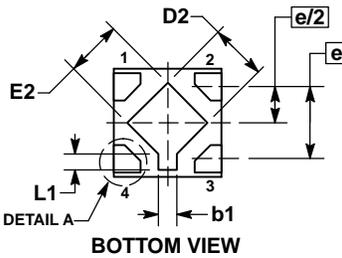
MILLIMETERS		
DIM	MIN	MAX
A	0.35	0.45
A1	0.00	0.05
A3	0.13	REF
b	0.25	0.35
b1	0.15	0.25
D	1.15	1.25
D2	0.58	0.68
E	1.15	1.25
E2	0.58	0.68
e	0.80	BSC
L	0.25	0.35
L1	0.13	0.23

GENERIC
MARKING DIAGRAM*



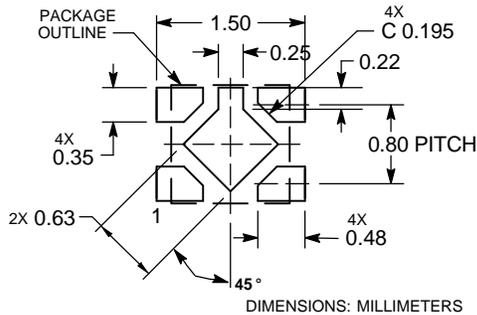
XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "μ", may or may not be present.



BOTTOM VIEW

RECOMMENDED
MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON04908G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	XDFN4, 1.2X1.2, 0.8P	PAGE 1 OF 2

